

Overview

HP 348 G7 Notebook PC



1. Internal Microphones (2)
2. Webcam LED
3. Webcam
4. Touchpad
5. Touchpad Button
6. Power Indicator LED

Left

7. Hard Drive Indicator LED
8. SD Card Slot
9. USB Type-C™ 3.1 Gen Port
10. USB 3.1 Gen 1 Port
11. Security Lock Slot (Lock sold separately)
12. Power Button

Overview



1. Power Connector
2. RJ-45/Ethernet Port
3. HDMI Port (Cable not included.)

Right

4. USB 3.1 Gen 1 Port
5. USB 3.1 Gen 1 Port
6. Audio Combo Jack

Overview

AT A GLANCE

- Preinstall with Windows 10 or FreeDOS
- Choice of 10th Generation Intel® Core™ i7, i5 and i3 processors
- Display include your choice of 35.56 cm (14") diagonal narrow bezel, AntiGlare, ultra-wide or standard view angle, HD or FHD
- Graphics include your choice of integrated Intel® graphics or switchable discrete graphics AMD Radeon™ 530
- Enhanced security features including Hardware TPM, Fingerprint Sensor² (select models), and security lock slot
- Passed 120,000 hours of reliability testing through HP's Total Test Process
- Integrated with 2 stereo speakers and dual array microphone for better audio experience
- Support dual storage, Solid State Drives up to 512 GB, and/or HDDs up to 1 TB
- Up to 32 GB total system memory
- Offers 720p HD webcam or no webcam edition for your options
- Full-size island-style, spill resistant keyboard and Touchpad with multi-touch gestures enabled, taps enabled as default
- Passed 13 MIL-STD 810G tests¹

1. MIL-STD-810G testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
2. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP 348 G7 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64¹
Windows 10 Pro 64 (National Academic only)²
Windows 10 Home 64¹
Windows 10 Home Single Language 64¹
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹
FreeDOS¹

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

PROCESSOR

Intel® Celeron® processors

Intel® Core™ i7-10510U processor with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i5-10210U processor with Intel® UHD Graphics (1.6 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i3-10110U processor with Intel® UHD Graphics (2.1 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel® Core™ i3-8130U with Intel® UHD Graphics 620 (2.2 GHz base frequency, up to 3.4 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel® Core™ i3-7020U with Intel® HD Graphics 620 (2.3 GHz, 3 MB L3 cache, 2 cores)^{3,4,6}

Processor Family

10th Generation Intel® Core™ i7 processor (i7-10510U)⁷

10th Generation Intel® Core™ i5 processor (i5-10210U)⁷

10th Generation Intel® Core™ i3 processor (i3-10110U)⁷

8th Generation Intel® Core™ i3 processor (i3-8130U)⁷

7th Generation Intel® Core™ i3 processor (i3-7020U)⁷

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Technical Specifications

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.
6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.
7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® UHD Graphics (i7-10510U, i5-10210U, and i3-10110U)⁸

Intel® UHD Graphics 620 (i3-8130U)⁸

Intel® HD Graphics 620 (i3-7020U)⁸

NOTE: See processor section for details.

Discrete

AMD Radeon™ 530 (2 GB GDDR5 dedicated)⁹

Supports

Support HD decode, DX12, HDMI 1.4

8. HD content required to view HD images.

9. AMD Dynamic Switchable Graphics technology requires an Intel processor, plus an AMD Radeon™ discrete graphics configuration and is not available on FreeDOS and Linux OS. With AMD Dynamic Switchable Graphics technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAY

Non-Touch

35.56 cm (14") diagonal HD SVA eDP anti-glare WLED-backlit slim-flat, 220 nits, 45% NTSC, one WLAN antenna (1366 x 768)^{8,10}

35.56 cm (14") diagonal HD SVA eDP anti-glare WLED-backlit slim-flat, 220 nits, 45% NTSC, two WLAN antennas (1366 x 768)^{8,10}

35.56 cm (14") diagonal FHD, UWVA IPS eDP anti-glare WLED-backlit slim-flat, 250 nits, 45% NTSC, one WLAN antenna (1920 x 1080)^{8,10}

Technical Specifications

35.56 cm (14") diagonal FHD UWVA IPS eDP anti-glare WLED-backlit slim-flat, 250 nits, 45% NTSC, two WLAN antennas (1920 x 1080) ^{8,10}

8. HD content required to view HD images.

10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage

500 GB 7200 rpm SATA¹¹

1 TB 5400 rpm SATA¹¹

Primary M.2 Storage

128 GB SATA TLC Solid State Drive¹¹

256 GB PCIe[®] NVMe[™] Value Solid State Drive¹¹

256 GB PCIe[®] NVMe[™] TLC Solid State Drive¹¹

512 GB PCIe[®] NVMe[™] Value Solid State Drive¹¹

Cache Memory

Intel[®] Optane[™] 16 GB Cache¹²

Only available with HDD

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

12. Intel[®] Optane[™] memory is sold separately. Intel[®] Optane[™] memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel[®] Core[™] processor or Intel[®] Xeon[®] processor E3-1200 V6 product family or higher, BIOS version with Intel[®] Optane[™] supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe[™] Spec 1.1, and an Intel[®] Rapid Storage Technology (Intel[®] RST) 15.5 driver.

MEMORY

Maximum Memory

32 GB DDR4-2666 SDRAM (only available for 10th Generation Intel[®] processors)

32 GB DDR4-2133 SDRAM¹³

Memory

32 GB DDR4-2666 SDRAM (2 X 16 GB) (Only available for 10th Generation Intel[®] processors)¹³

16 GB DDR4-2666 SDRAM (1 X 16 GB) (Only available for 10th Generation Intel[®] processors)¹³

8 GB DDR4-2666 SDRAM (1 x 8 GB) (Only available for 10th Generation Intel[®] processors)¹³

4 GB DDR4-2666 SDRAM (1 x 4 GB) (Only available for 10th Generation Intel[®] processors)¹³

Technical Specifications

32 GB DDR4-2133 SDRAM (2 X 16 GB)¹³

16 GB DDR4-2133 SDRAM (1 X 16 GB)¹³

8 GB DDR4-2133 SDRAM (1 x 8 GB)¹³

4 GB DDR4-2133 SDRAM (1 x 4 GB)¹³

Memory Slots

2 SODIMM

Both slots are customer accessible / upgradeable

DDR4 PC4 SODIMMS runs at 2666 on 10th Gen Intel® (CML) processors and runs at 2133 on 8th/7th Gen Intel (KBL and KBL-R) processors

Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Realtek 802.11a/b/g/n/ac (1x1) and Bluetooth® 4.2 Combo¹⁴

Realtek 802.11a/b/g/n/ac (2x2) and Bluetooth® 5 Combo¹⁴

Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™^{14,15}

Intel® Dual Band Wi-Fi 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro™^{15*}

Miracast

Support for Miracast¹⁶

Ethernet

Integrated 10/100/1000 GbE

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC¹⁷

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

15. Only available for 10th Generation Intel® processors

16. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

17. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

* Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported

AUDIO/MULTIMEDIA



Technical Specifications

Audio

2 Integrated Stereo Speakers
Integrated Dual Array Microphone

Camera

HP TrueVision HD Camera^{8,18}

8. HD content required to view HD images.

18. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full size island-style spill-resistant keyboard

Pointing Device

Touchpad with multi-touch gesture support

Function Keys

ESC: System Information

F1: Windows Help

F2: Brightness Down

F3: Brightness Up

F4: Display Switching

F5: Blank

F6: Speaker Mute

F7: Volume Down

F8: Volume Up

F9: Previous track/section

F10: Starts, Pauses, or resumes playback

F11: Next track/section

F12: Airplane mode (Wireless feature on or off).

SOFTWARE AND SECURITY

Software

HP Support Assistant¹⁹

Native Miracast Support²⁰

Security Management

Security Lock

HP Drivelock²¹

Hardware TPM and Firmware TPM 2.0

Technical Specifications

Fingerprint Sensor (select models)²²

19. HP Support Assistant requires Windows and Internet access.

20. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

21. Supports primary storage only

22. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

POWER

Power Supply

HP Smart 65 W EM External AC power adapter²³

HP Smart 65 W External AC power adapter²³

HP Smart 45 W External AC power adapter²³

Primary Battery

HP Long Life 3-cell, 41 Wh Li-ion²⁴

Support HP fast charge technology²⁵

Power Cord

3-wire plug – 1 m²³

3-wire plug - 1.8 m²³

Battery Life

Up to 13 hours (UMA, CML-U processor, HD display, 4 GB*1 memory, SSD)²⁶

Battery Weight

0.19 lb

0.41 kg

23. Availability may vary by country.

24. Battery is internal and not replaceable by customer. Serviceable by warranty.

25. Recharges the battery up to 90% within 90 minutes or up to 50% within 45 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

26. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <http://www.bapco.com> for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.3 lbs²⁷

Starting at 1.5 kg²⁷



Technical Specifications

Does not include power adapter.

Product Dimensions (W x D x H)

8.89 x 12.76 x 0.783 in

22.59 x 32.4 x 1.99 cm

27. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB type C (support USB3.1 gen1 /data-transfer only)

2 USB 3.1 gen 1

1 USB 3.1 gen 1 (support charging/power delivery)

1 HDMI 1.4²⁸

1 RJ-45

1 AC power

1 Headphone/microphone combo jack

Expansion Slots

1 multi-format digital media reader

Supports SD, SDHC, SDXC

28. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.²⁹

29. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V
	Average Operating Power	Win 10
	Integrated Graphics	5.28 W
	Max Operating Power	Discrete < 65W UMA < 45W
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%
Shock	Operating	40 G, 2 ms duration, half-sine
	Non-operating	240 G, 2 ms duration, half-sine
Random Vibration	Operating	1.043 grms
	Non-operating	3.5 grms
Altitude (unpressurized)	Operating	-15 m to 3048 m (-50 ft to 10000 ft)
	Non-operating	-15 m to 12192 m (-50 ft to 40000 ft)
Planned Industry Standard Certifications	UL	Yes
	CSA	No
	FCC Compliance	Yes
	ENERGY STAR®	No, but compliant with ENERGY STAR ³⁰
	EPEAT®	EPEAT® 2019 Silver in U.S. ³¹
	ICES	Yes
	Australia	No
	NZ A-Tick Compliance	No
	CCC	Yes
	Japan VCCI Compliance	No
	KC	No
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	No
	CIT	No
	GOST	No
Saudi Arabian Compliance (ICCP)	No	
SABS	No	
UKRSERTCOMPUTER	No	

Technical Specifications

30. Configurations of the HP 348 Notebook PC that are ENERGY STAR® certified are identified as HP 348 Notebook PC ENERGY STAR® on HP websites and on <http://www.energystar.gov>.

31. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14 inch diagonal FHD WLED Anti-Glare (1920 x 1080) slim-flat (3.0 mm), UWVA, eDP, Narrow Bezel	Outline Dimensions (W x H x D)	320.9 x 205.6 (max)
	Active Area	309.31 x 173.99
	Weight	290g (max)
	Diagonal Size	14 inch
	Thickness	3.0 mm max.
	Interface	eDP 1.2 (2 Lane)
	Surface Treatment	Anti-Glare (AG)
	Touch Enabled	No
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nit typ
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85	

14 inch diagonal HD SVALED-backlight; 220 cd/m2; 45% sRGB (1366 x 768)	Outline Dimensions (W x H x D)	316.2 x 198 (mm) max (with PCB Board)
	Active Area	309.4 x 173.95 (mm)
	Weight	280 g max.
	Diagonal Size	14.0 (inch)
	Thickness	3.0 (mm) max
	Interface	eDP 1.2
	Surface Treatment	Anti-glare (AG)
	Touch Enabled	None
	Contrast Ratio	500:1 (typical)

Technical Specifications

Refresh Rate	60 Hz
Brightness	220 nit typical
Pixel Resolution	1366 x 768 (HD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	45% of NTSC
Color Depth	6 bits
Viewing Angle	45/45/20/45

STORAGE AND DRIVES

500 GB 7200 rpm SATA Hard Drive

Drive Weight	0.21 lbs (95 g)
Rotation speed	7200 rpm
Cache Buffer	Up to 128MB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	600 MB/s
Seek Time	Single Track: 2 ~ 1.5 ms Average: 11 ~ 13 ms Maximum: 18 ~ 22 ms
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
Security Features	ATA Security
Features	S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard Drive

Drive Weight	0.21 lbs (94 g)- 0.21 lbs (95 g)
Rotation speed	5400 rpm
Cache Buffer	Up to 128MB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	600 MB/s
Seek Time	Single Track: 2ms; Average: 12 ~ 13 ms; Maximum: 18 ~ 22 ms
Logical Blocks	1,953,525,168

Technical Specifications

Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
Security Features	ATA Security
Features	S.M.A.R.T., NCQ, Ultra DMA

128 GB 2280 M2 SATA-3 TLC Solid State Drive

Drive Weight	M.2 2280
Rotation speed	128 GB
Cache Buffer	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Interface	0.01 lb (6 g) ~ 0.02 lb (10 g)
Transfer Rate	ATA-8, SATA 3.0
Seek Time	Up To 535 MB/s
Logical Blocks	Up To 515 MB/s
Operating Temperature	250,069,680
Security Features	32° to 158°F (0° to 70°C) [ambient temp]
Features	DIPM; TRIM; DEVSLP

256 GB 2280 M2 PCIe NVMe Value Solid State Drive

Form Factor	M.2 2280
Capacity	256GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Interface	PCIe NVMe Gen3x2
Maximum Sequential Read	Up to 1500 MB/s
Maximum Sequential Write	Up to 1000 MB/s
Logical Blocks	500,118,192
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	TRIM, L1.2

Form Factor	M.2 2280
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Technical Specifications

256 GB PCIe NVMe TLC Solid State Drive	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3x4
	Maximum Sequential Read	Up to 2500 MB/s
	Maximum Sequential Write	Up to 1000 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	TRIM, L1.2	

512 GB 2280 M2 PCIe NVMe Value Solid State Drive	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.01 lb (6 g) ~ 0.02 lb (10 g)
	Interface	PCIe NVMe Gen3x2
	Maximum Sequential Read	Up to 1500 MB/s
	Maximum Sequential Write	Up to 1000 MB/s
	Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	TRIM, L1.2	

NETWORKING/COMMUNICATIONS

Intel® 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹ non-vPro	Wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h

Technical Specifications

	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified modules
Frequency Band	<ul style="list-style-type: none"> •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security³	<ul style="list-style-type: none"> • IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum

Technical Specifications

Power Consumption	<ul style="list-style-type: none"> • 802.11ac VHT160(5GHz): +11.5dBm minimum • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity ³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum 				
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8 g 2. Type 126: 1.3 g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	<p>LED Amber – Radio OFF</p> <p>LED White – Radio ON</p>				

Technical Specifications

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan

Technical Specifications

BT4.2 ESR08 Compliance
 LE Secure Connection- Basic/Full
 LE Privacy 1.2 –Link Layer Privacy
 LE Privacy 1.2 –Extended Scanner Filter Policies
 LE Data Packet Length Extension
 FAX Profile (FAX)
 Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

**Intel® Wi-Fi 6⁴ AX201 +
 Bluetooth® 5 (802.11
 a/b/g/n/ac/ax
 2 x 2, non-vPro,
 supporting gigabit file
 transfer speeds)
 non-vPro**

Wireless LAN Standards

IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11ax
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability

Wi-Fi modules

Frequency Band

- 802.11b/g/n/ax
2.402 – 2.482 GHz
- 802.11a/n/ac/ax
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
- 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

Technical Specifications

160MHz)

Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security³	<ul style="list-style-type: none"> • IEEE and WiFi 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum

Technical Specifications

	<ul style="list-style-type: none"> • 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED Off – Radio ON

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
4. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available	Legacy: 0~79 (1 MHz/CH)

Technical Specifications

Channels	BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP) ² Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Technical Specifications

<p>802.11a/b/g/n/ac (1 x 1) Wireless LAN Standards</p> <p>Wi-Fi® and Bluetooth®</p> <p>4.2 Combo¹</p>	<p>IEEE 802.11a</p> <p>IEEE 802.11b</p> <p>IEEE 802.11g</p> <p>IEEE 802.11n</p> <p>IEEE 802.11ac</p> <p>IEEE 802.11d</p> <p>IEEE 802.11e</p> <p>IEEE 802.11h</p> <p>IEEE 802.11i</p> <p>IEEE 802.11k</p> <p>IEEE 802.11r</p> <p>IEEE 802.11v</p>
<p>Interoperability</p>	<p>Wi-Fi CERTIFIED®</p>
<p>Frequency Band</p>	<ul style="list-style-type: none"> •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
<p>Data Rates</p>	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
<p>Modulation</p>	<p>Direct Sequence Spread Spectrum</p> <p>BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM</p>
<p>Security³</p>	<ul style="list-style-type: none"> • IEEE 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
<p>Network Architecture Models</p>	<p>Ad-hoc (Peer to Peer)</p> <p>Infrastructure (Access Point Required)</p>
<p>Roaming</p>	<p>IEEE 802.11 compliant roaming between access points</p>

Technical Specifications

Output Power²	<ul style="list-style-type: none"> • 802.11b: +14dBm minimum • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum • 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum 				
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard				
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm				
Weight	Type 2230: 2.8 g				
Operating Voltage	3.3v +/- 9%				
Temperature	<table> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				

Technical Specifications

LED Activity	LED Amber – Radio OFF LED Off – Radio ON
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1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising

Technical Specifications

LE L2CAP Connection Oriented Channels
 Train Nudging & Interlaced Scan
 BT4.2 ESR08 Compliance
 LE Secure Connection- Basic/Full
 LE Privacy 1.2 –Link Layer Privacy
 LE Privacy 1.2 –Extended Scanner Filter Policies
 LE Data Packet Length Extension
 FAX Profile (FAX)
 Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

**RTL8822CE 802.11ac
 2 x 2 Wi-Fi® and
 Bluetooth® 5**

Wireless LAN Standards

IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability

Wi-Fi CERTIFIED®

Frequency Band

- 802.11b/g/n
 2.402 – 2.482 GHz
- 802.11a/n/ac
 4.9 – 4.95 GHz (Japan)
 5.15 – 5.25 GHz
 5.25 – 5.35 GHz
 5.47 – 5.725 GHz
 5.825 – 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)

Technical Specifications

Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security³	<ul style="list-style-type: none"> • IEEE 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to

Technical Specifications

	support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (–10° to 70° C)
	Non-operating	–40° to 176° F (–40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON	

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Technical Specifications

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

POWER

HP 45 W Smart AC adapter

Dimensions (H x W x D) 95.0 x 40.0 x 26.5 mm

Weight 200 g +/- 10 g

[Not including power cord. Power cord varies by country.](#)

Input 100 to 240 VAC

Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230Vac

Input frequency range 48 ~ 63 Hz

Technical Specifications

Output	Input AC current	Max. 1.4 A at 90 Vac
	Output power	45 W
	DC output	19.5 V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	<8.0A
Connector	C6, 4.5mm barrel type	
Environmental Design	Operating temperature	32°F to 95°F (0°C to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°C to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	<p>CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards – IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals – C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF – over 200,000 hours at 25°C ambient condition.</p>	

HP 65 W Smart AC adapter	Dimensions (H x W x D)	90.0 x 51 x 28.5 mm
	Weight	230 g +/- 10 g
Input	Not including power cord. Power cord varies by country.	
	100 to 240 VAC	
	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
	Input frequency range	48 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
Output	Output power	65 W
	DC output	19.5 V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	<11.0 A
	Connector	C6, 4.5mm barrel type
Environmental Design	Operating temperature	32°F to 95°F (0°C to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°C to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives.	

Technical Specifications

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV;
Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP EM 65 W Smart AC adapter	Dimensions (H x W x D)	102 x 55 x 30 mm
	Weight	250 g +/- 10 g
	Input	100 to 240 VAC
		Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range 48 ~ 63 Hz
		Input AC current Max. 1.7 A at 90 Vac
	Output	Output power 65 W
		DC output 19.5 V
		Hold-up time 5 ms at 115 Vac input
		Output current limit <11.0 A
	Connector	C6, 4.5mm barrel type
	Environmental Design	Operating temperature 32°F to 95°F (0°C to 35°C)
		Non-operating (storage) temperature -4°F to 185°F (-20°C to 85°C)
		Altitude 0 to 16,400 ft (0 to 5000m)
	Humidity 20% to 95%	
	Storage Humidity 10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

HP 3-cell Long Life Li-Ion (41 WHr)	Dimensions (H x W x D)	6.0 x 186.35 x 90.2 mm (0.236 x 7.33 x 3.55 inch)		
	Weight	0.19 kg (0.418 lb)		
	Cells/Type	3cell Lithium-Ion Polymer cell / 515974 Prismatic cell 496080		
	Energy	Voltage	11.55 V/11.4 V/11.34 V	
		Amp-hour capacity	3.63 Ah/3.6 Ah/3.62 Ah	
		Watt-hour capacity	41 Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
Operating (Discharging)		14° to 122° F (-10° to 60° C)		

Technical Specifications

Optional Travel Battery Available No

FINGERPRINT SENSOR

Model	Elan eFSA80ST touch sensor
Mobile Voltage Operation	2.65 V to 3.6 V
Operating Temperature	32° to 95° F (0° to 35° C)
Current Consumption Image	50 mA peak
Low Latency Wait for Finger	<900 uA
Capture Rate	20 cm/sec
ESD Resistance	IEC 61000-4-2 (+15KV)
Detection Matrix	508 dpi / 4 x 4 mm sensor area
FRR (False Reject Rate) / FAR (False Acceptance Rate)	FRR ~ 2% @ 1:50 K FAR

Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Messenger Case (up to 17.3")	H1D25AA
Docking	HP 3005pr USB3 Port Replicator	Y4H06AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock NF (non-flash)	3DV65AA
	HP USB-C/A Universal Dock G2	5TW13AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP Stereo USB Headset	T1A67AA
HP Stereo 3.5mm Headset	T1A66AA	
Power	HP 65W Smart AC Adapter	H6Y89AA
	HP 45W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y88AA
	HP 45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	HP 65W 4.5mm non-EM AC Adapter (India only)	3FF84AA
Storage	HP Mobile USB DVDRW	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP UC Speaker Phone	4VW02AA

Summary of Changes

Date of change:	Version History:		Description of change:
February 18, 2020	From v1 to v2	Updated	Keyboard
February 27, 2020	From v2 to v3	Updated	Copyright and footnote for fingerprint sensor.
April 12, 2020	From v3 to v4	Updated	Weights and Ports sections
April 22, 2020	From v4 to v5	Updated	Networking /Communications section
April 22, 2021	From V5 to V6	Updated	Memory section
May 28, 2021	From V6 to V7	Deleted	HP USB-C Dock G5 (5TW10AA) HP USB-C Mini Dock (1PM64AA)

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